

# **General Description**

The WSD30L40DN is the highest performance trench P-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD30L40DN meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

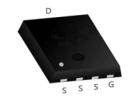
# **Product Summery**

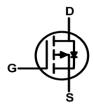
BVDSS	RDSON	ID
-30V	11mΩ	-40A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

# **DFN3X3-8 Pin Configuration**





### **Absolute Maximum Ratings**

		Rating		
Symbol	Parameter	10s	Steady State	Units
V <sub>DS</sub>	Drain-Source Voltage	-	30	V
$V_{GS}$	Gate-Source Voltage	<u>+</u>	20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	_	40	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-	-25	
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-14.5	-12	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-10.5	-9.8	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-7	-70	
EAS	Single Pulse Avalanche Energy <sup>3</sup> 81		mJ	
I <sub>AS</sub>	Avalanche Current -18		-18	
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation⁴	Total Power Dissipation <sup>4</sup> 32.9		W
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>4</sup>	3.6	3.1	W
T <sub>STG</sub>	Storage Temperature Range	-55 t	-55 to 150	
TJ	Operating Junction Temperature Range	-55 t	-55 to 150	

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>		75	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> (t ≤10s)		40	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		3.8	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS}$ =0V , $I_D$ =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =-1mA		-0.0232		V/°C
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-20A		11	14	0
R <sub>DS(ON)</sub>		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-10A		18	24	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V -V I - 250::A	-1.3	-1.8	-2.3	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=-250uA$		4.6		mV/℃
	Dunin Course Leglana Cumant	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			-1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			-5	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20 V$ , $V_{DS}$ = $0 V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-30A		15		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		9		Ω
$Q_g$	Total Gate Charge (-4.5V)	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-20A		30		
$Q_gs$	Gate-Source Charge			1.2		nC
Q <sub>gd</sub>	Gate-Drain Charge			11		
T <sub>d(on)</sub>	Turn-On Delay Time			11		
Tr	Rise Time	$V_{DD}$ =-15V , $V_{GS}$ =-10V , $R_{G}$ =6 $\Omega$		11		20
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =-1A ,R <sub>L</sub> =15Ω		101		ns
T <sub>f</sub>	Fall Time			60		
Ciss	Input Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		1380		
C <sub>oss</sub>	Output Capacitance			280		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			217		

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.5mH , I <sub>AS</sub> =-18A	78			mJ

### **Diode Characteristics**

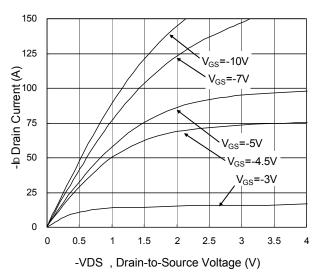
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				-70	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1	V
t <sub>rr</sub>	Reverse Recovery Time	IF=-20A,dI/dt=100A/µs, Tյ=25℃		20		nS
Qrr	Reverse Recovery Charge			8		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch $^2$  FR-4 board with 2OZ copper,  $t \le 10$  sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =-25V, $V_{GS}$ =-10V,L=0.5mH, $I_{AS}$ =-18A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



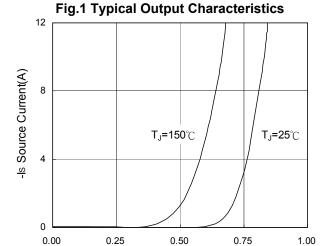


Fig.3 Forward Characteristics of Reverse

-V<sub>SD</sub>, Source-to-Drain Voltage (V)

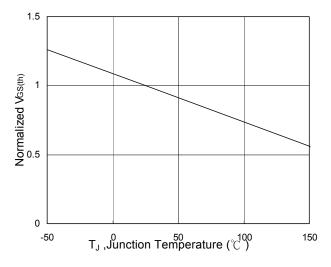


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs.  $T_{\text{J}}$ 

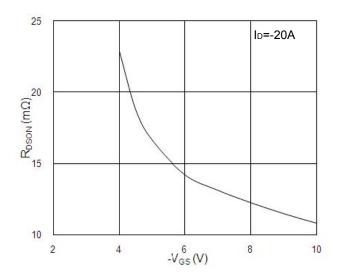


Fig.2 On-Resistance vs. G-S Voltage

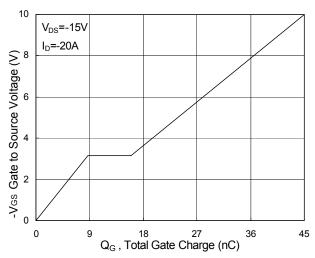


Fig.4 Gate-Charge Characteristics

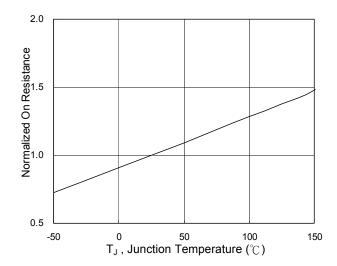
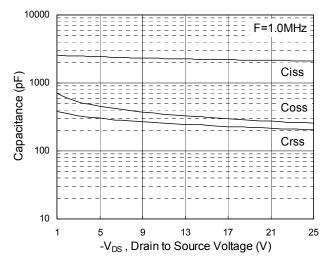


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>







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Fig.7 Capacitance

Fig.8 Safe Operating Area

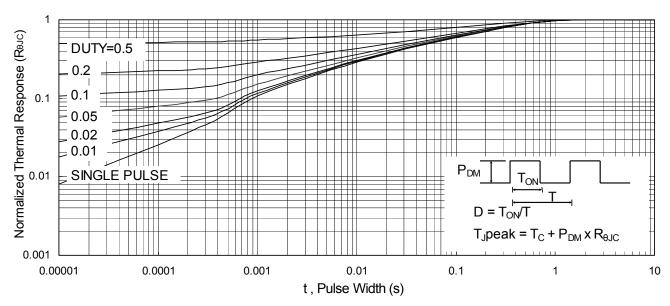
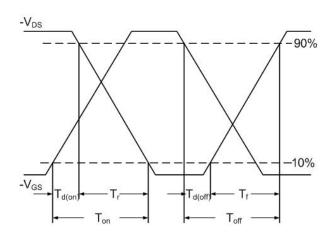


Fig.9 Normalized Maximum Transient Thermal Impedance



-I<sub>AS</sub>

EAS=  $\frac{1}{2}$  L x (-I<sub>AS</sub><sup>2</sup>)x  $\frac{-BV_{DSS}}{-BV_{DSS}-(-V_{DD})}$ 

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform



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